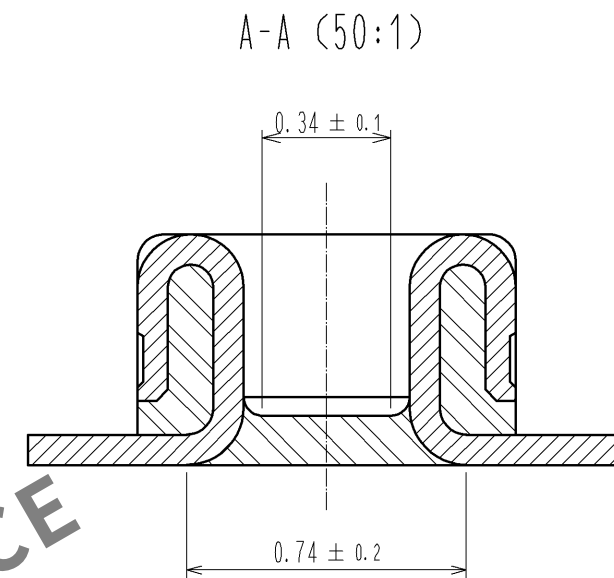
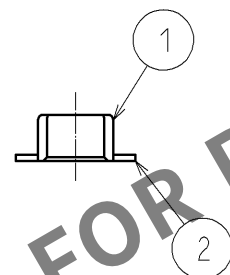
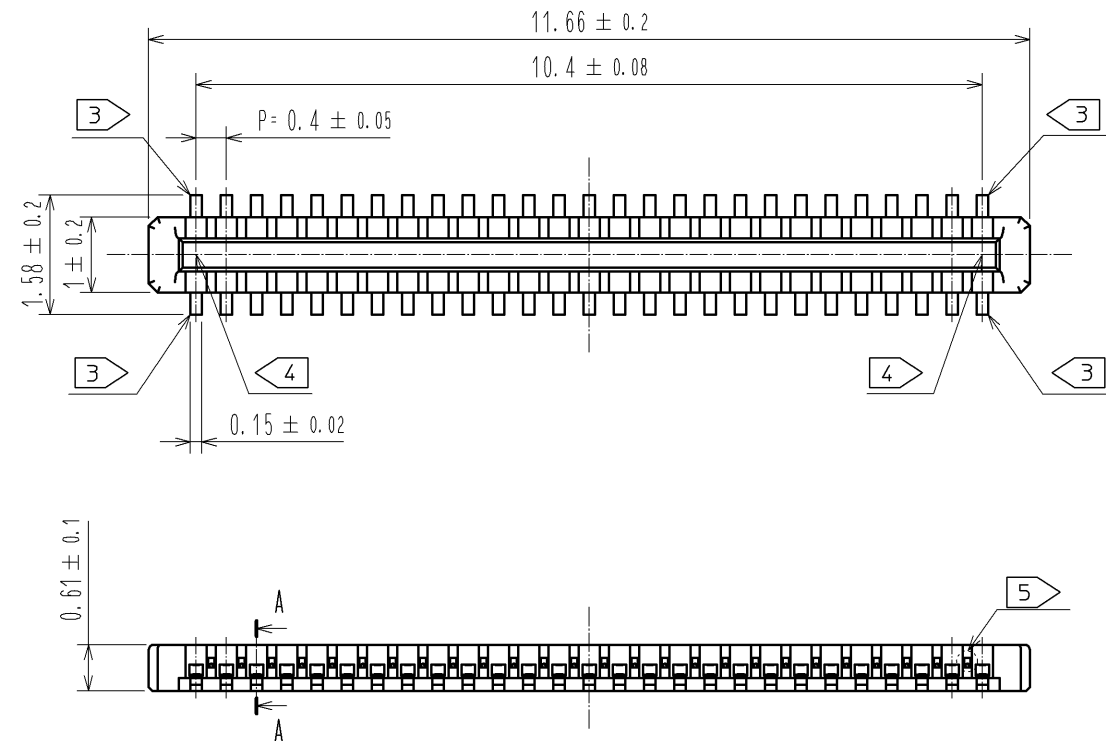
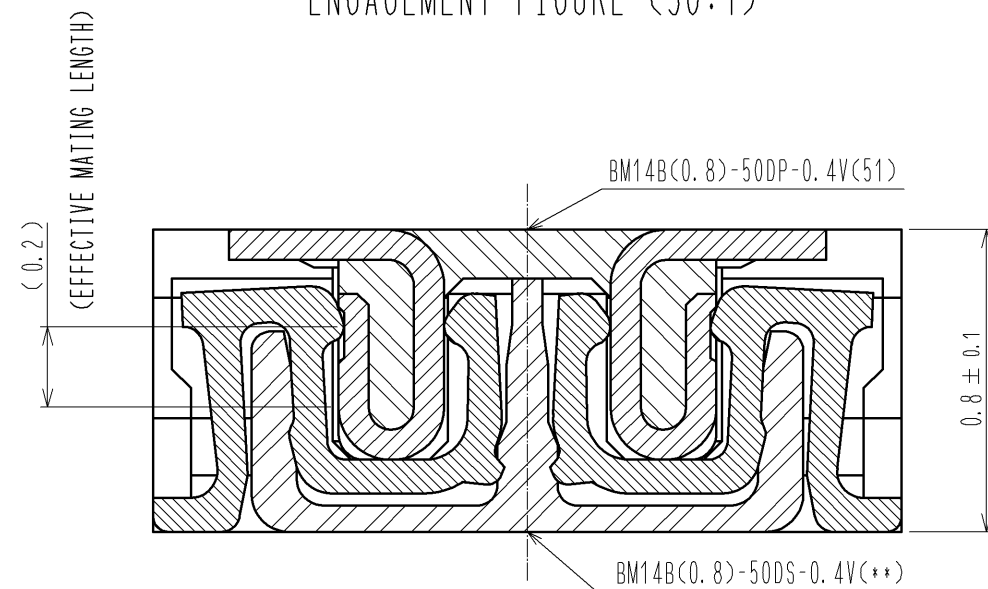




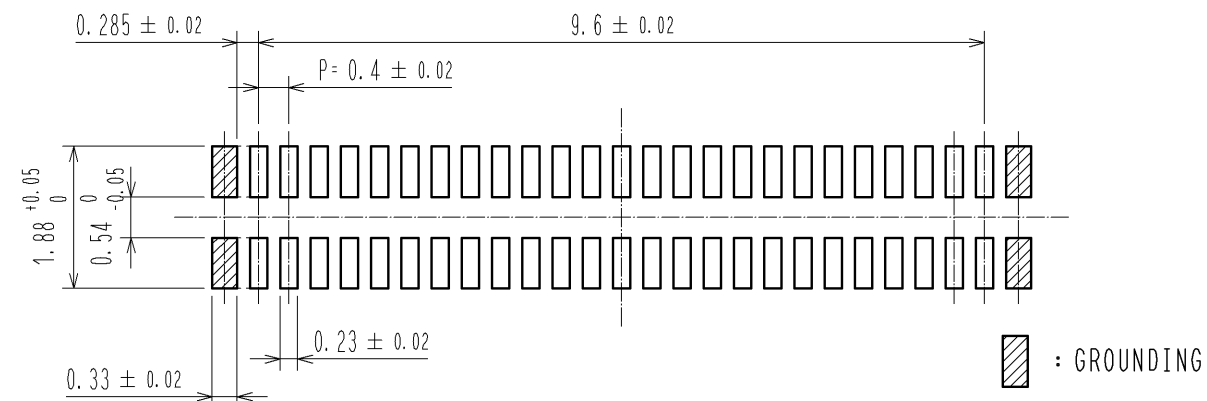
ENGAGEMENT FIGURE (50:1)



- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3. EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
5. A PART OF THE WALL COULD BE NOTCHED.

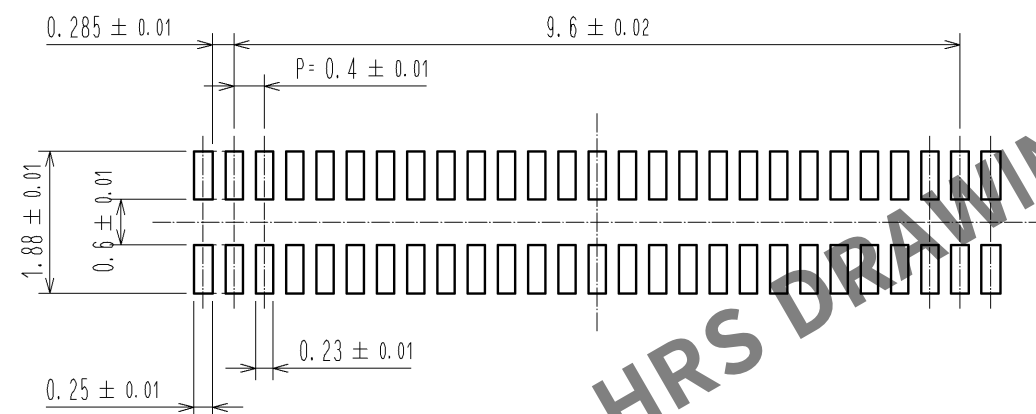
3	PS	CLEAR (ENBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE 10:1	COUNT 1	DESCRIPTION OF REVISIONS	DESIGNED
		APPROVED : KH. IKEDA	13. 09. 03	DRAWING NO.	EDC3-319851-01
		CHECKED : TS. MIYAZAKI	13. 09. 03	PART NO.	BM14B(0.8)-50DP-0.4V(51)
		DESIGNED : SH. HOSODA	13. 09. 03	CODE NO.	CL684-8016-7-51
		DRAWN : SH. HOSODA	13. 09. 03		
		DATE			

◆ RECOMMENDED PCB LAYOUT

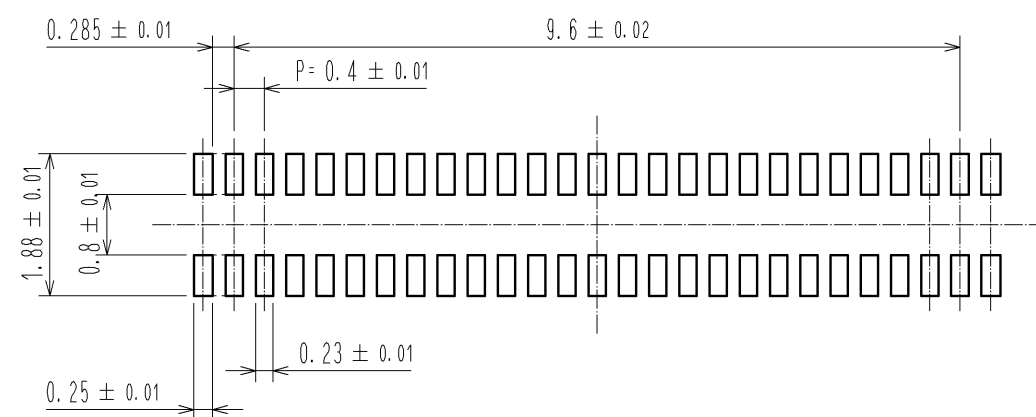


◆ RECOMMENDED METAL MASK DIMENSIONS

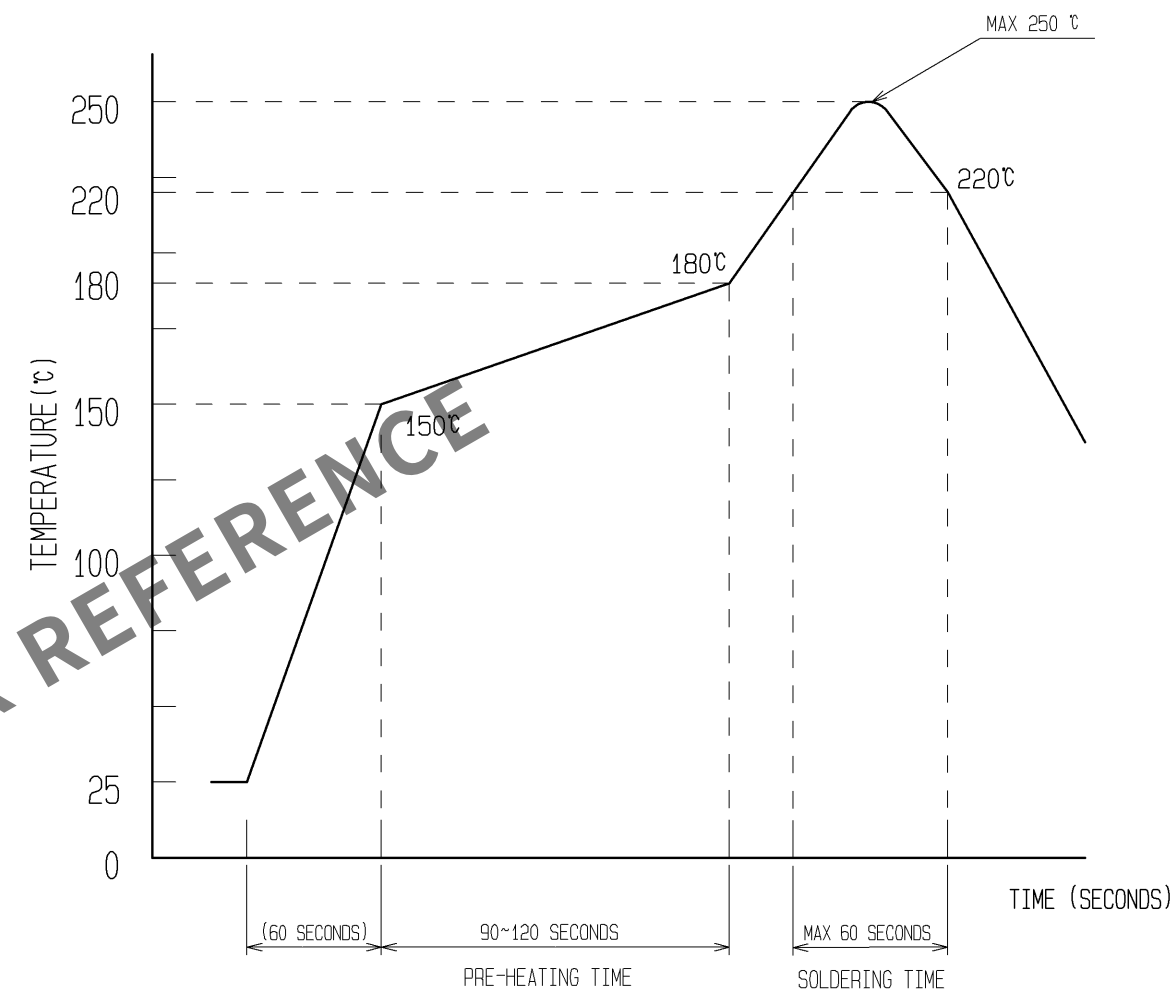
METAL MASK THICKNESS : $100 \mu\text{m}$



METAL MASK THICKNESS : $120 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C, 60 SEC. MAX.

(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C

PRE-HEAT TEMPERATURE(MAX): 180°C

PRE-HEAT TIME: 90~120 sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-319851-01
PART NO.	BM14B(0.8)-50DP-0.4V(51)
CODE NO.	CL684-8016-7-51

2/3

